

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Hitoshi Takanashi	10/13/2004
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Sumitomo Wiring Systems, Ltd.
<b>Street Address:</b>	1-14, Nishisuehiro-cho
<b>City:</b>	Yokkaichi-shi
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	510-8503
<b>Name:</b>	Advics Co., Ltd.
<b>Street Address:</b>	2-1, Showa-cho
<b>City:</b>	Kariya, Aichi
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	448-8688
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	10912612
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(212)725-2452
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	2127252450
<b>Email:</b>	email@casella-hespos.com
<b>Correspondent Name:</b>	CASELLA & HESPOS LLP
<b>Address Line 1:</b>	274 Madison Avenue - Suite 1703
<b>Address Line 4:</b>	New York, NEW YORK 10016
<b>NAME OF SUBMITTER:</b>	Gerald E. Hespos

CH \$40.00 10912612

Total Attachments: 1  
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**ASSIGNMENT**

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignee, (1) SUMITOMO WIRING SYSTEMS, LTD. (2) ADVICS CO., LTD., a corporation organized under the laws of Japan, located (1) 1-14, Nishisuehiro-cho, Yokkaichi-shi, Mie 510-8503 Japan (2) 2-1, Showa-cho, Kariya, Aichi 448-8688, Japan, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignee the entire right, title and interest in and to the invention or improvement entitled "A CONSTRUCTION FOR CONNECTING A CIRCUIT BOARD AND AN ELECTRICAL PART, A BRAKE OIL PRESSURE CONTROL UNIT"

said invention being fully described and/or claimed in the application for Letters Patent of the United States of America, executed this date, in and for the United States and all foreign countries, the same to be held and enjoyed by said assignee, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

**And Said Assignee Is Hereby Authorized** to make application for and to receive Letters Patent for said invention in any of said countries at its election.

**And By This Covenant The Undersigned** will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patents which may be granted therefor in said Assignee, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patents to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignee, its successors, assigns or other legal representatives.

**And The Commissioner Of Patents Is Hereby Authorized And Requested** to issue any and all Letters Patent of the United States for said invention, to said assignee.

October 13, 2004

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Date

Hitoshi Takanashi  
Hitoshi TAKANASHI

\_\_\_\_\_  
Date

\_\_\_\_\_  
Takao TSUNOOKA

\_\_\_\_\_  
Date

\_\_\_\_\_  
Yasuhito SEKIHARA

\_\_\_\_\_  
Date

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**PATENT**